Amendments to the Specification:

Please replace original paragraph [13] with the following paragraph [13]:

[0013] The heat sink 25 is integrated to the circuit board 20 as follows. A standoff press 40 is fitted into one of four holes or bores 45 in the heat sink 25 from the bottom of the heat sink base 30. A panel screw 50, along with a tension spring 55, is inserted into the hole 45 from the top of the heat sink base 30. The panel screw 50 is then rotated past the threaded part 60 of the standoff press 40. The tension spring 55 will then push the panel screw 50 up against the standoff press 40, holding the heat sink 25 in place. The tension spring 55 acts to retract the panel screw 50 up into the standoff press 40 only when the heat sink 25 is not assembled into a system 75. The tension spring 55 also helps retract the panel screw 50 up into the standoff press 40 during disassembly, giving notice to an individual that the panel screw 50 has been unthreaded from the system 75. When the panel screw 50 is activated, the tension spring 55 is compressed into the space between the bottom threaded portion of the screw [[head]] 70 and the standoff press 40, hiding it from view.

Please replace original paragraph [14] with the following paragraph [14]:

[0014] Basically, the panel screw 50 goes through the tension spring 55 and the panel screw 50 and tension spring 55 go down through to the standoff press 40. The standoff press 40 is press fit into the heat sink base 30. Ideally, the standoff press 40 can be ¼" in diameter. However, the standoff press 40 diameter may vary based on the application. Furthermore, the standoff press 40 does not have to be press fit, they can be threaded or attached in any other method as long as they are rigidly attached. The standoff press 40 is attached to the bottom of the heat sink base 30 and the amount the standoff press 40 protrudes from the bottom of the heat sink base 30 is dependent on what CPU package (CPU and socket mechanical stackup) the heat sink will be placed on. The height of the panel screw 50 can be varied to accommodate different packages and stackups. The present invention is tolerant of variation in the height of the integrated circuit 15.

Please replace paragraph [15] with the following paragraph [15]:

[0015] The standoff press 40 may contain a counter-bore 65. The ~~counterbore~~ counter-bore 65 enables the threaded portion of the panel screw 50 to hide when the tension spring 55 pulls the panel screw 50 upwards in the standoff press 40. This also enables the standoff press 40 to contain the panel screw 50 and to clamp down on the tension spring 55 when the heat sink 25 is attached to the integrated circuit 15 for reliable thermal performance.

Please replace paragraph [16] with the following paragraph [16]:

[0016] Fig. 4 illustrates a cross sectional view of the heat sink. As illustrated, the tension spring 55 retains the panel screw 50 in the standoff press 40 and basically pulls the panel screw 50 upward. The bottom threaded portion of the screw head 70 is pulled up inside the standoff press 40. Therefore, the ~~standoff counterbore~~ counter-bore 65 allows the threaded portion of the panel screw 50 to recess into the standoff [[65]] press 40 via spring tension. And as mentioned before, this functions as an indicator that the panel screw 50 has been disengaged from the system ~~chassis~~ 75 during disassembly.

Please replace original paragraph [17] with the following paragraph [17]:

[0017] When assembling, the individual screws the heat sink 25 down. The panel screw 50 comes out from the recesses in the standoff press 40 and the panel screw 50 engages the chassis of the integrated circuit 15. Now, the standoff press 40 and the tension spring 55 are now compressed and hidden ~~in the counterbore 65~~. The bottom threaded portion of the screw head 70 now engages the top of the heat sink base 30.